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U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

To the Honorable Commissioner

103388528

ached original documents or copy thereof.

## 1. Name of conveying parties

Hisao TANAKA, Masaki HIROSE, Takayoshi KAWAMURA,  
Hiroshi SAITOU, Yoshiho GOTOH, Tatsushi BANNALAdditional name(s) of conveying party(ies)  
attached? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies)

SONY CORPORATION  
1-7-1 Konan, Minato-ku  
Tokyo, 108-0075, JapanMATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.  
1006, Oaza Kadoma, Kadoma-shi  
Osaka 571-8501, JapanAdditional name(s) & address(es) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

- ☒
- Assignment
- 
- ☐
- Security Agreement
- 
- ☐
- Merger
- 
- ☐
- Change of Name
- 
- ☐
- Other

Execution Date(s): January 13, 2006, January 16, 2006, January 20,  
2006, December 1, 2005, December 2, 2005 and December 1, 2005.

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No. 10/560,152Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WILLIAM S. FROMMER  
Internal Address: FROMMER LAWRENCE & HAUG LLP  
Street Address: 745 FIFTH AVENUE  
City: NEW YORK State: NY Zip: 10151

## 6. Total number of applications and patents involved

1

## 7. Total fee (37 CFR 3.41)

\$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account 50-0320

## 8. Deposit account number:

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William S. Frommer, Reg. No. 25,506

Name of Person Signing

Signature

March 22, 2007

Date

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PATENT  
REEL: 019095 FRAME: 0466

**ASSIGNMENT**

WHEREAS, I, as below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

**INFORMATION PROCESS APPARATUS AND METHOD, PROGRAM, AND RECORD MEDIUM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address; *umx*

AND WHEREAS, SONY CORPORATION, a Japanese Corporation, with offices at ~~1-7-1 KONAN, MINATO-KU, TOKYO, 108-0075, JAPAN~~ *7-35 Kitashinagawa 6-chome, Shinagawa-Ku, Tokyo, 141-0001, Japan* and MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., a Japanese Corporation, with offices at 1006, Oaza Kadoma, Kadoma-shi, Osaka 57108501, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP2004/008502, International Filing Date: June 10, 2004.

This assignment executed on the dates indicated below.

**Hisao TANAKA**

Name of sole or 1st inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of sole or 1st inventor

*Hisao Tanaka*

Signature of sole or 1st inventor

*January 13, 2006*

Date of this assignment

**Masaki HIROSE**

Name of 2nd joint inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of 2nd joint inventor

*Masaki Hirose*

Signature of 2nd joint inventor

*January 16, 2006*

Date of this assignment

## ADDITIONAL INVENTORS

**Takayoshi KAWAMURA**

Name of 3rd joint inventor

Execution date of U.S. Patent Application

**Kanagawa, Japan**

Residence of 3rd joint inventor

*Takayoshi Kawamura**January 20, 2006*

Signature of 3rd joint inventor

Date of this assignment

**Hiroshi SAITOU**

Name of 4th joint inventor

Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 4th joint inventor

Signature of 4th joint inventor

Date of this assignment

**Yoshiho GOTOU**

Name of 5th joint inventor

Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 5th joint inventor

Signature of 5th joint inventor

Date of this assignment

**Tatsushi BANNAI**

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Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 6th joint inventor

Signature of 6th joint inventor

Date of this assignment

## ADDITIONAL INVENTORS

**Takayoshi KAWAMURA**

Name of 3rd joint inventor

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**Kanagawa, Japan**

Residence of 3rd joint inventor

Signature of 3rd joint inventor

Date of this assignment

**Hiroshi SAITOU**

Name of 4th joint inventor

Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 4th joint inventor

*Hiroshi Saitou*

Signature of 4th joint inventor

*Dec. 1, 2005*

Date of this assignment

**Y. G. GOTOH**  
**Yoshiho GOTOU**

Name of 5th joint inventor

Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 5th joint inventor

*Yoshiho Gotoh*

Signature of 5th joint inventor

*December 2, 2005*

Date of this assignment

**Tatsushi BANNAI**

Name of 6th joint inventor

Execution date of U.S. Patent Application

**Osaka, Japan**

Residence of 6th joint inventor

*Tatsushi Bannai*

Signature of 6th joint inventor

*Dec. 1, 2005*

Date of this assignment